



# SOT873-1

plastic, thermal enhanced very thin small outline package; 8 terminals; 0.65 mm pitch; 3.3 mm x 3.3 mm x 1 mm body

30 January 2017

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN3333-8
Package type industry code	DFN3333-8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	19-4-2010
Manufacturer package code	SOT873

Table 1. Package summary

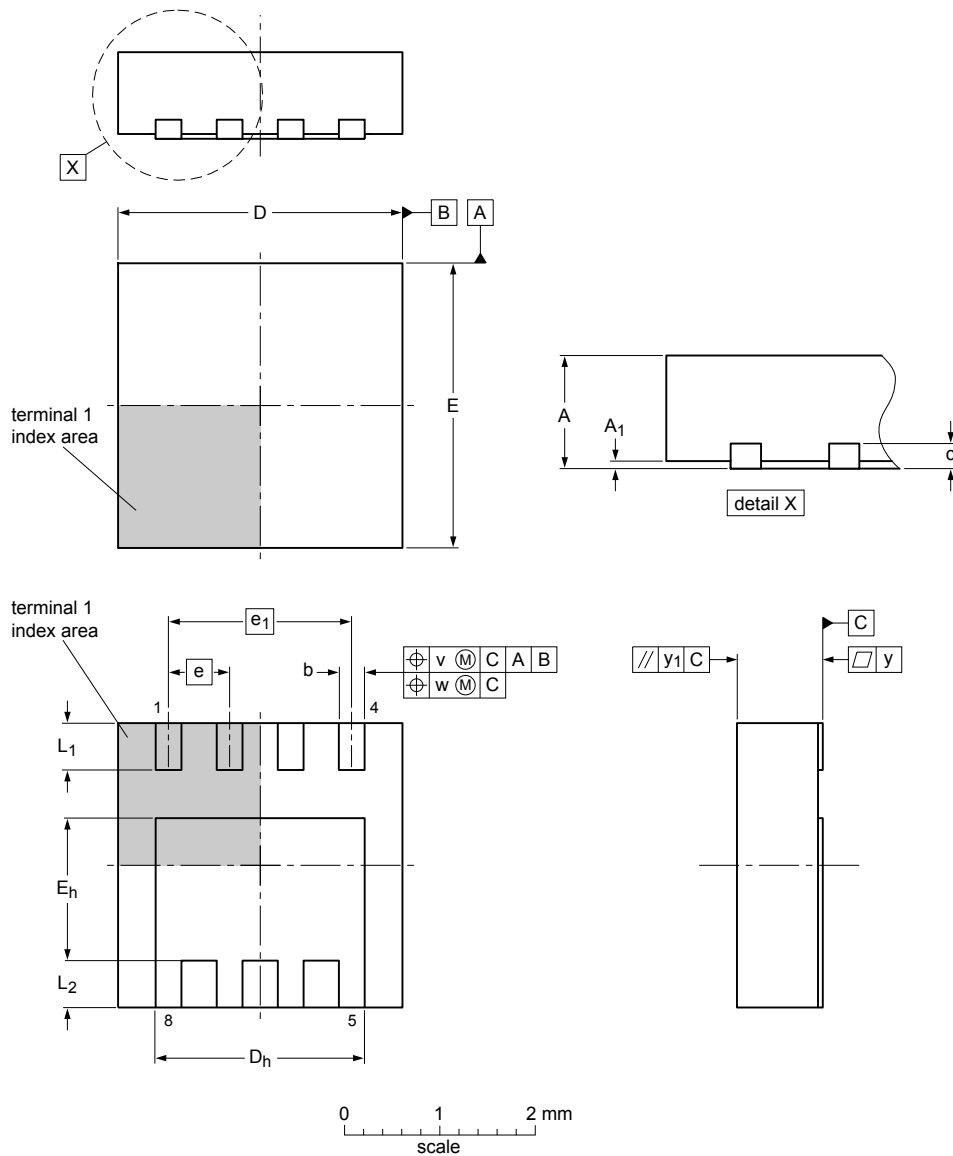
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.2	-	3.3	3.4	mm
E	package width	3.2	-	3.3	3.4	mm
A	seated height	-	-	-	1	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	8	-	

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## 2. Package outline

DFN3333-8: plastic thermal enhanced very thin small outline package; no leads; 8 terminals; body 3.3 x 3.3 x 1.0 mm

SOT873-1



DIMENSIONS (mm are the original dimensions)

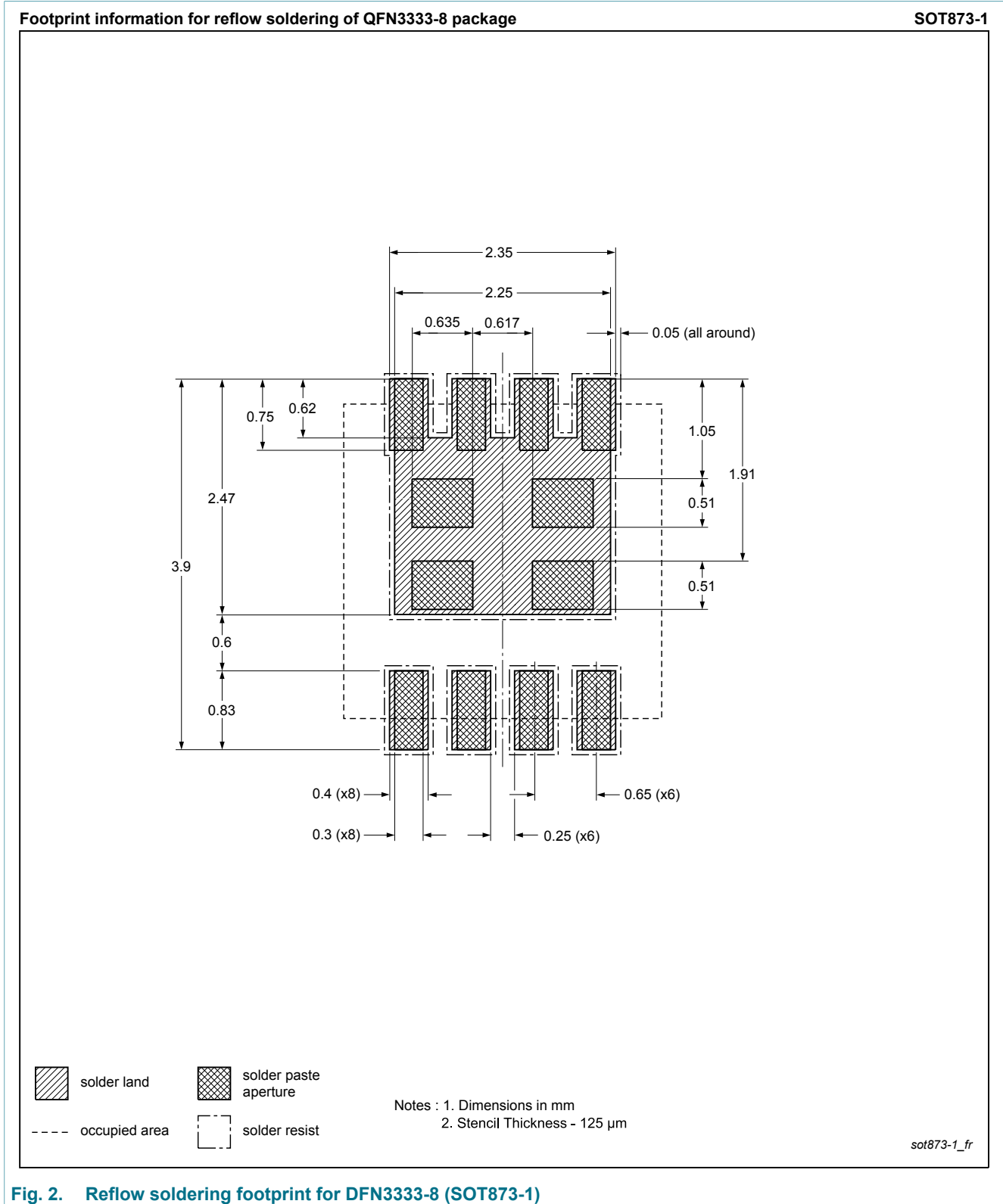
UNIT	A <sub>max.</sub>	A <sub>1</sub>	b	c	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	L <sub>1</sub>	L <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.45 0.25	0.2	3.4 3.2	2.4 2.2	3.4 3.2	1.80 1.58	0.65	1.95	0.55 0.45	0.52 0.35	0.1	0.05	0.1	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT873-1	---	---	---			40-04-19 11-12-01

Fig. 1. Package outline DFN3333-8 (SOT873-1)

plastic, thermal enhanced very thin small outline package; 8 terminals; 0.65 mm pitch; 3.3 mm x 3.3 mm x 1 mm body

### 3. Soldering



plastic, thermal enhanced very thin small outline package; 8 terminals; 0.65 mm pitch; 3.3 mm x 3.3 mm  
x 1 mm body

## 4. Legal information

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